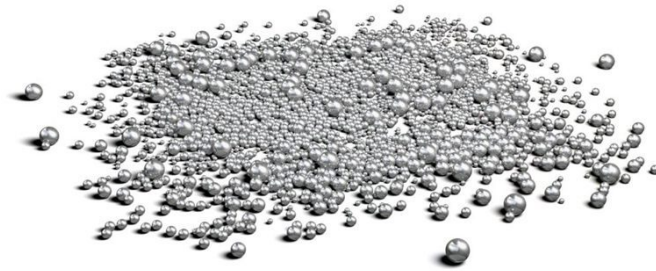
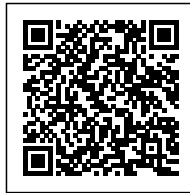


LEAD-FREE SOLDER BALLS SN96.5/AG3/CU0.5 (250.000PCS)



SKU: SBLF



BGA REBALLING BALLS - SN/AG/CU ALLOY

Lead-free solder balls for BGA reballing, available in 9 different diameters.

Alloy composition: Sn96.5/Ag3/Cu0.5.

Packaging: 250.000 pieces jar.

Available sizes (Diameter): 0,25mm – 0,30mm – 0,35mm – 0,40mm – 0,45mm – 0,50mm – 0,55mm – 0,60mm – 0,76mm.

VARIATIONS

SKU	Description	Diameter
071958C		0,25mm
071958D		0,30mm
071958E		0,35mm
071958F		0,40mm
071958G		0,45mm



SKU	Description	Diameter
071958H		0,50mm
071958I		0,55mm
071958L		0,60mm
071958B		0,76mm